Tool ID: 206
Tool Location: 107

Equipment Information Sheet

Trion Minilock III ICP Etcher

Manager: Jeremy Clark 607-254-6487
Backup: Mac McMurdy 607-254-4813

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- User must remain in the lab while the plasma is running
- System uses Chlorine & Boron Trichloride

USAGE RESTRICTIONS

- No buddy system restrictions for normal operation

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 30 minutes

- No scheduling restrictions

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No high vapor pressure materials (Pb, ITO, etc.)
- No gold exposed to the plasma
- Pieces should be mounted to sapphire carrier wafer (4)

Last Updated: 03/24/2021